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200mW, NPN Small Signal Transistor

FEATURES

- Epitaxial planar die construction
- Surface mount device type
- Moisture sensitivity level 1
- Matte Tin(Sn) lead finish with Nickel(Ni) underplate
- Pb free and RoHS complian
- Green compound (Halogen free) with suffix "G" on packing code and prefix "G" on date code

MECHANICAL DATA

- Case: SOT- 323 small outline plastic package
- Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed: 260°C/10s
- Weight: 0.005 grams (approximately)











1 Base 2 Emitter

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Power Dissipation	P _D	200	mW	
Collector-Base Voltage	V _{CBO}	50	V	
Collector-Emitter Voltage	V _{CEO}	45	V	
Emitter-Base Voltage	V _{EBO}	5	V	
Collector Current	I _C	0.5	А	
Thermal Resistance, Junction to Ambient	R _{θJA}	625	K/W	
Junction and Storage Temperature Range	T_J,T_STG	-55 to +150	°C	

Notes: 1. Transistor mounted on a FR4 printed-circuit board

PARAME	SYMBOL	MIN	MAX	UNIT	
Collector-Base Breakdown Voltage at I _C = 10 μA		V _{(BR)CBO}	50	-	V
Collector-Emitter Breakdown Voltage at I _C = 10 mA		V _{(BR)CEO}	45	-	V
Emitter-Base Breakdown Voltage	lown Voltage at I _E = 10 μA		5	-	V
Collector Cut-off Current	at V _{CB} = 20 V	I _{CBO}	-	100	nA
Emitter Cut-off Current	at V _{EB} = 5 V	I _{EBO}	-	100	nA
Collector-Emitter Saturation Voltage	at $I_C = 500 \text{mA}$ $I_B = 50 \text{ mA}$	V _{CE(sat)}	-	0.7	V
Transition Frequency	$V_{CE} = 5 \text{ V } I_{C} = 10 \text{ mA f} = 100 \text{MHz}$	f_T	100	-	MHz
at V _{CE} = 1 '					
	-16W		100	250	
DC Current Gain	-25W	h _{FE}	160	400	
	-40W		250	600	
at V _{CE} = 1 '	V , I _C = 500 mA		40		



RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

Fig.1Total Power Dissipation $P_{tot} = f(T_S)$

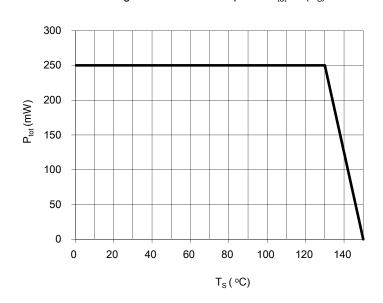


Fig.2 Permissible Pulse Load $R_{\theta JA} = f(tp)$

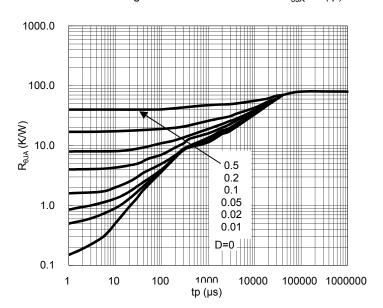


Fig.3 Permissible Pulse Load P_{totmax} / P_{totDC} = f(tp)

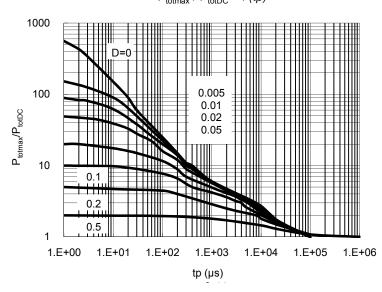
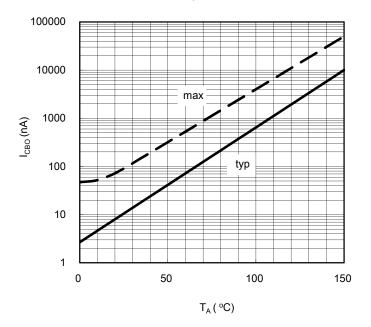


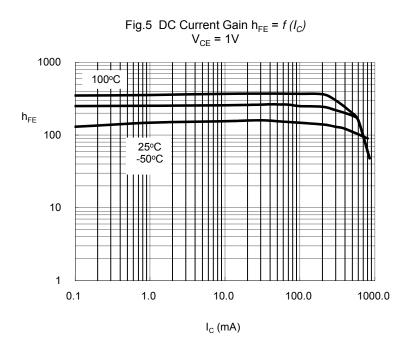
Fig. 4 Coolector Cutoff Current $I_{CBO} = f(T_A)$ $V_{CB} = 25V$

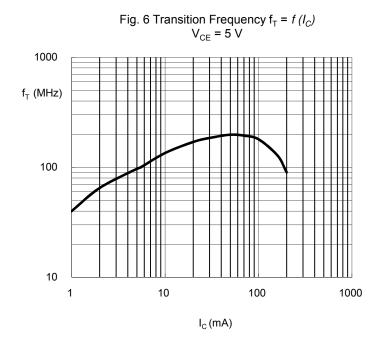


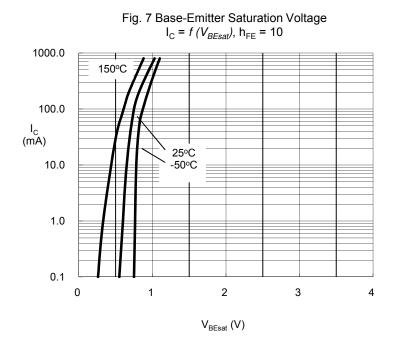


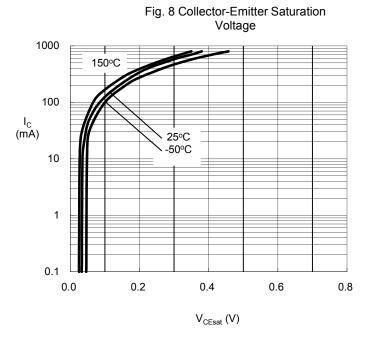
RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)









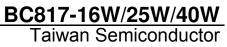




ORDERING INFORMATION					
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	MARKING
BC817-16W	RF	G	SOT-323	3K / 7" Reel	6CR
BC817-25W	RF	G	SOT-323	3K / 7" Reel	6CS
BC817-40W	RF	G	SOT-323	3K / 7" Reel	6CT

EXAMPLE				
PREFERRED P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
BC817-16W RFG	BC817-16W	RF	G	Green compound

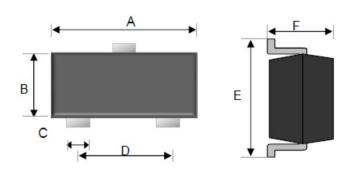
Document Number: DS_S1404010 Version: D15





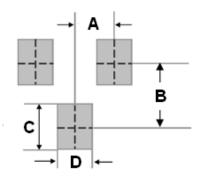
DIMENSIONS

SOT-323



DIM.	Unit	(mm)	Unit (inch)	
DIIVI.	Min	Max	Min	Max
Α	1.80	2.20	0.07	0.09
В	1.15	1.35	0.05	0.05
С	0.15	0.40	0.01	0.02
D	1.20	1.40	0.05	0.06
Е	2.00	2.45	0.08	0.10
F	0.80	1.10	0.03	0.04

SUGGEST PAD LAYOUT



DIM.	Unit(mm)	Unit(inch)
DIW.	Тур.	Тур.
Α	0.65	0.026
В	1.6	0.063
С	0.8	0.031
D	0.8	0.031



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